

Title (en)

METHOD AND DEVICE FOR THE CONTROLLED ELECTROLYTIC TREATMENT OF THIN LAYERS

Title (de)

VERFAHREN UND VORRICHTUNG ZUM GESTEUERTEN ELEKTROLYTISCHEN BEHANDELN VON DÜNNEN SCHICHTEN

Title (fr)

PROCÉDÉ ET DISPOSITIF PERMETTANT LE TRAITEMENT ÉLECTROLYTIQUE COMMANDÉ DE COUCHES MINCES

Publication

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Application

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Priority

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Abstract (en)

[origin: WO2010133220A2] The invention relates to a method and a device for electroplating a material (1) comprising an electric contact in the outer edge thereof, especially for electroplating substrates, e.g. as a wafer in a cup plater. Conventional methods result in a radial layer thickness difference, with a maximum in the edge region, when the starting layers are thin and the material has a large diameter. In order to obtain an even electroplating result, at least two electrolytic partial cells are formed which are supplied with current by respective electroplating current sources (9') and (9'') that can be individually adjusted. The partial cathode (12') and the associated partial anode (7') are supplied in the region of the diametrically remote partial cathode (12''). Conversely, the partial cathode (12'') is supplied via the base layer of the partial cathode (12'). The required leveling of the layer thickness distribution is inter alia carried out by alternate different adjustments of the quantity of the electroplating current of the two partial cells and by the electrodes (7, 12) that rotate relative to each other.

IPC 8 full level

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